

Method of dividing wafer into diesAbstract

A method of dividing a wafer, having on one side a device area with a plurality of devices partitioned by a plurality of division lines and a peripheral marginal area with no devices formed around the device area, into dies is provided. The method comprises: attaching an adhesive tape for protecting devices on the wafer to the one side of the wafer, the adhesive tape adhering to at least some, optionally all, of the devices; connecting a carrier for supporting the adhesive tape to the side of the adhesive tape being opposite to the side in contact with the devices by connecting means; grinding that side of the wafer being opposite the one side for adjusting the wafer height; and cutting the wafer along the division lines. The method is characterized by locating the connecting means completely outward of the device area of the wafer in a top view thereon.

Figure 3